



Board Characteristics

0. All dimensions are given in inches unless specified otherwise.
1. Material FR4 with Tg>170C, E.g. FR406
2. Minimum trace width: 0.006" and clearance: 0.005" on Signal_1,6 (Top and Bottom);
3. Minimum trace width and clearance: 0.005" on Signal_2,3,4,5,7,8,9,10 (all stripline);
4. 1 oz copper for all power layers and for Signal_1,2 (Top and Bottom)
1/2 oz copper for Stripline trace layers (Signal_2,3,4,5,7,8,9,10).
5. Immersion Gold over copper, with min. Ni: 2.5-5 um; Au: 0.05-0.2 um.
Apply Solder Mask over bare copper.
6. Board Thickness: 0.093 +/- 0.008
7. Mill the Top and Bottom of board on the solder side to a thickness of 0.063" +/- 0.008
8. Silkscreen on Component and Solder Sides.
9. 45 degree chamfer.
10. FHS tolerances: +/- 0.002 unless specified otherwise.
11. Interlayer spacing as specified
12. Zc=55 Ohm +/- 5 Ohm for 0.005" stripline and 0.006" microstrip traces on all layers.
Perform TDR test for all signal layers.
Present TDR test results for all signal layers.

BOARD'S DRILL SCHEDULE

DRILL SYMBOL	DRILL SIZE	COUNT	PLATED	Tolerance	COMMENT
○	.014	4641	YES	---	
⊞	.015748031	144	YES	---	
⊙	.018	5	YES	---	
⊞	.035	42	YES	---	
⊖	.037	18	YES	---	
⊞	.041	475	YES	---	
⊕	.042	20	YES	---	
□	.05	5	YES	---	
	.057	18	YES	---	
	.062	4	YES	---	
	.062992126	8	YES	---	
	.086614173	2	NO	---	
	.106	6	NO	---	
	.125	2	YES	---	
	.12795276	6	YES	---	3
	.15	5	NO	---	

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES ARE: FRACTIONS DECIMALS ANGLES .XX .XXX DO NOT SCALE DRAWING	CONTRACT NO.		UNIVERSITY OF CHICAGO ELECTRONICS DEVELOPMENT GROUP		
	APPROVALS		DATE	TITLE	
	DRAWN	M. Bogdan	4/25/2017	14-BIT ADC Board Specification Drawing	
	CHECKED	M. Bogdan	4/25/2017	SIZE	FSCM NO.
FINISH	ISSUED		DWG. NO.	2606	REV. D
SIMILAR TO	ACT. WT	CALC. WT	SCALE	1/2	SHEET